

Title (en)
METHOD FOR MANUFACTURE OF PRINTED CIRCUIT BOARDS.

Title (de)
HERSTELLUNGSVERFAHREN VON GEDRUCKTEN SCHALTUNGEN.

Title (fr)
PROCEDE DE FABRICATION DE CARTES A CIRCUITS IMPRIMES.

Publication
EP 0233201 A4 19871130 (EN)

Application
EP 86904002 A 19860609

Priority
US 76381285 A 19850808

Abstract (en)
[origin: WO8700938A1] Printed circuit boards having solder coated pads and through-holes (140) and bare copper traces (160) protected by a directly applied solder mask (260) or by a coating of non-reflowable metal and a solder mask thereover, are manufactured by a process which avoids the need for tin-lead stripping and the need for separate application and leveling of molten solder. In the preferred process, liquid resists (240) are applied to circuit boards having tin-lead (220) over copper plated holes (140) and pads so as to define and etch-protect bare copper traces (160) of desired pattern circuitry (as well as other desired configurations). Copper areas other than those protected by the etch-resist (240) and tin-lead plating (220) are etched away, the etch-resist (240) removed and solder mask (260) applied over the bare copper traces (160) or other desired bare copper areas or, alternatively, to bare copper first coated with a non-reflowable metal. The tin-lead plating (220) is then preferably reflowed and solidified to provide the pads and through-holes with solder coating.

IPC 1-7
G03C 5/00; H05K 3/10; H05K 3/42

IPC 8 full level
H05K 3/24 (2006.01); **H05K 3/34** (2006.01); **H05K 3/42** (2006.01); **H05K 3/06** (2006.01); **H05K 3/28** (2006.01)

CPC (source: EP)
H05K 3/243 (2013.01); **H05K 3/3473** (2013.01); **H05K 3/427** (2013.01); **H05K 3/064** (2013.01); **H05K 3/244** (2013.01); **H05K 3/28** (2013.01); **H05K 2201/09736** (2013.01); **H05K 2203/043** (2013.01)

Citation (search report)

- [X] GB 1410780 A 19751022 - EXACTA CIRCUITS LTD
- [X] CA 1054259 A 19790508 - GEN ELECTRIC CANADA
- [X] EP 0127794 A2 19841212 - ANT NACHRICHTENTECH [DE]
- See references of WO 8700938A1

Designated contracting state (EPC)
AT BE CH DE FR GB IT LI LU NL SE

DOCDB simple family (publication)
WO 8700938 A1 19870212; AU 5956286 A 19870305; CA 1258138 A 19890801; EP 0233201 A1 19870826; EP 0233201 A4 19871130; JP S63500837 A 19880324

DOCDB simple family (application)
US 8601270 W 19860609; AU 5956286 A 19860609; CA 515260 A 19860801; EP 86904002 A 19860609; JP 50322886 A 19860609